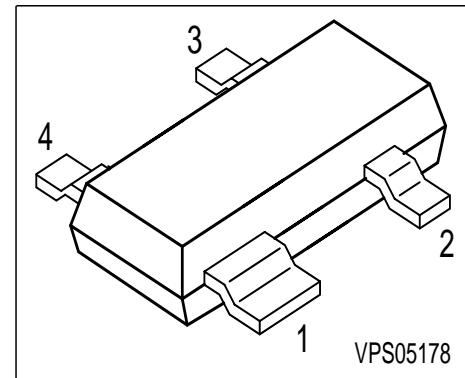
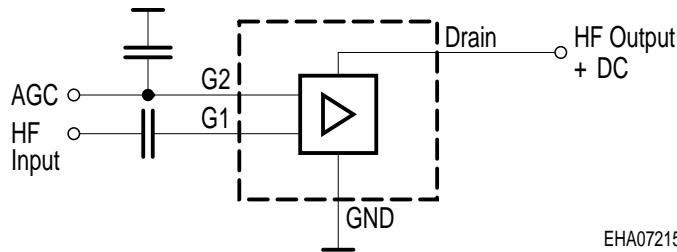


## Silicon N-Channel MOSFET Tetrode

- For low noise, high gain controlled input stages up to 1GHz
- Operating voltage 12V
- Integrated stabilized bias network



**ESD:** Electrostatic discharge sensitive device, observe handling precaution!

Type	Marking	Pin Configuration				Package
BF1012S	NYs	1 = S	2 = D	3 = G2	4 = G1	SOT143

### Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	16	V
Continuos drain current	$I_D$	25	mA
Gate 1/gate 2 peak source current	$\pm I_{G1/2SM}$	10	
Gate 1 (external biasing)	$+V_{G1SE}$	3	V
Total power dissipation, $T_S \leq 76^\circ\text{C}$	$P_{tot}$	200	mW
Storage temperature	$T_{stg}$	-55 ... 150	°C
Channel temperature	$T_{ch}$	150	

### Thermal Resistance

Channel - soldering point <sup>1)</sup>	$R_{thchs}$	$\leq 370$	K/W
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<sup>1</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

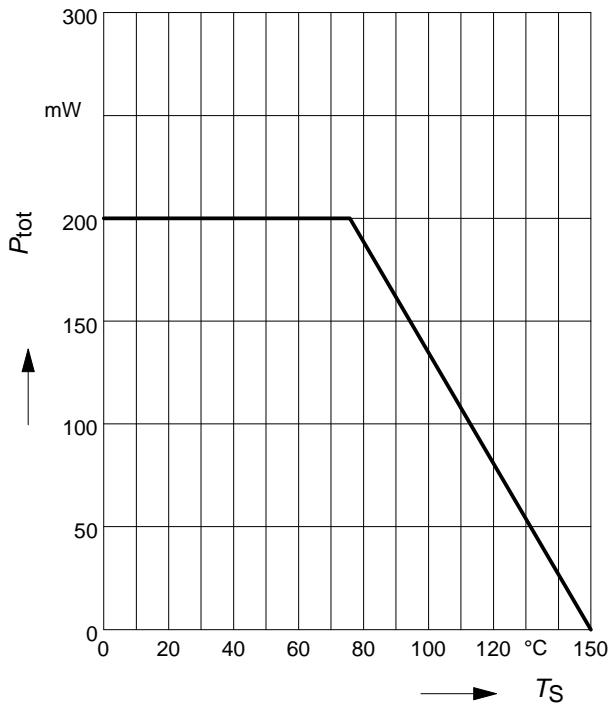
### Note:

**It is not recommended to apply external DC-voltage on Gate 1 in active mode.**

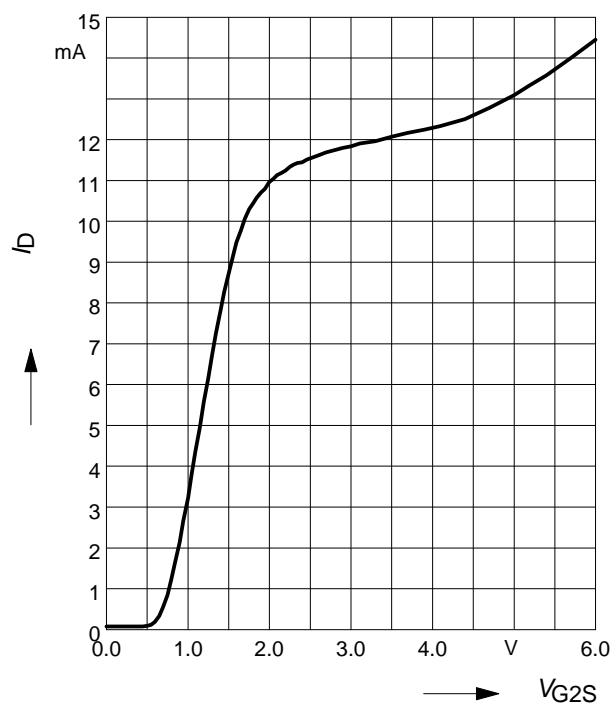
**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC characteristics</b>					
Drain-source breakdown voltage $I_D = 300 \mu\text{A}, V_{G1S} = 0 \text{ V}, V_{G2S} = 0 \text{ V}$	$V_{(\text{BR})\text{DS}}$	16	-	-	V
Gate 1 - source breakdown voltage $+I_{G1S} = 10 \text{ mA}, V_{G2S} = 0 \text{ V}, V_{DS} = 0 \text{ V}$	$+V_{(\text{BR})\text{G1SS}}$	8	-	12	
Gate 2 source breakdown voltage $\pm I_{G2S} = 10 \text{ mA}, V_{G1S} = 0 \text{ V}, V_{DS} = 0 \text{ V}$	$\pm V_{(\text{BR})\text{G2SS}}$	10	-	16	
Gate 1 source current $V_{G1S} = 6 \text{ V}, V_{G2S} = 0 \text{ V}$	$+I_{G1\text{SS}}$	-	-	60	$\mu\text{A}$
Gate 2 source leakage current $\pm V_{G2S} = 8 \text{ V}, V_{G1S} = 0 \text{ V}, V_{DS} = 0 \text{ V}$	$\pm I_{G2\text{SS}}$	-	-	50	nA
Drain current $V_{DS} = 12 \text{ V}, V_{G1S} = 0, V_{G2S} = 6 \text{ V}$	$I_{D\text{SS}}$	-	-	500	$\mu\text{A}$
Operating current (selfbiased) $V_{DS} = 12 \text{ V}, V_{G2S} = 6 \text{ V}$	$I_{D\text{SO}}$	8	12	-	mA
Gate 2-source pinch-off voltage $V_{DS} = 12 \text{ V}, I_D = 100 \mu\text{A}$	$V_{G2\text{S(p)}}$	-	0.9	-	V
<b>AC characteristics</b>					
Forward transconductance (self biased) $V_{DS} = 12 \text{ V}, V_{G2S} = 6 \text{ V}$	$g_{fs}$	26	30	-	mS
Gate 1-input capacitance (self biased) $V_{DS} = 12 \text{ V}, V_{G2S} = 6, f = 1 \text{ MHz}$	$C_{g1\text{ss}}$	-	2.1	2.7	pF
Output capacitance (self biased) $V_{DS} = 12 \text{ V}, V_{G2S} = 6, f = 1 \text{ MHz}$	$C_{dss}$	-	0.9	-	
Power gain (self biased) $V_{DS} = 12 \text{ V}, V_{G2S} = 6, f = 800 \text{ MHz}$	$G_{ps}$	18	22	-	dB
Noise figure (self biased) $V_{DS} = 12 \text{ V}, V_{G2S} = 6, f = 800 \text{ MHz}$	$F_{800}$	-	1.4	-	dB
Gain control range (self biased) $V_{DS} = 12 \text{ V}, V_{G2S} = 6 \dots 0\text{V}, f = 800 \text{ MHz}$	$\Delta G_{ps}$	40	50	-	

**Total power dissipation**  $P_{\text{tot}} = f(T_S)$

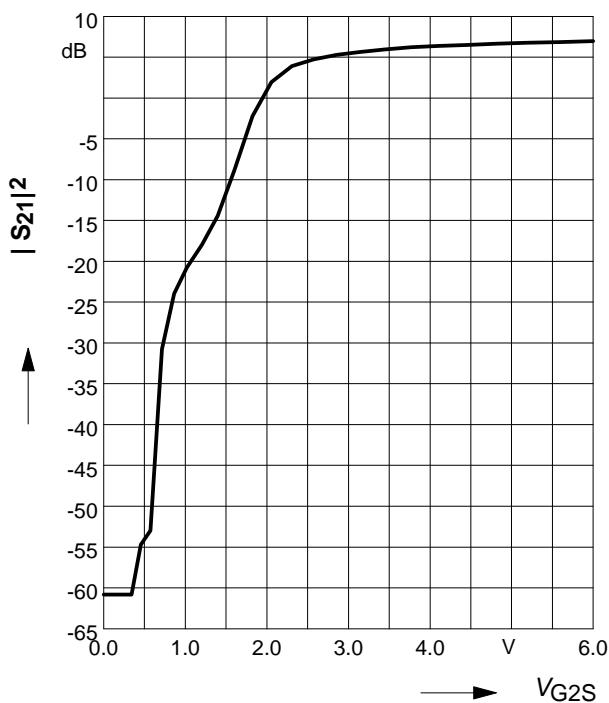


**Drain current**  $I_D = f(V_{G2S})$



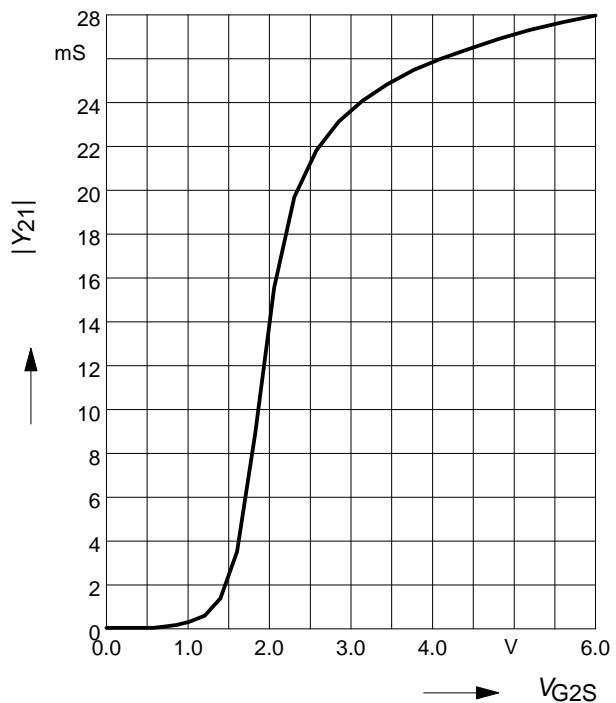
**Insertion power gain**

$$|S_{21}|^2 = f(V_{G2S})$$

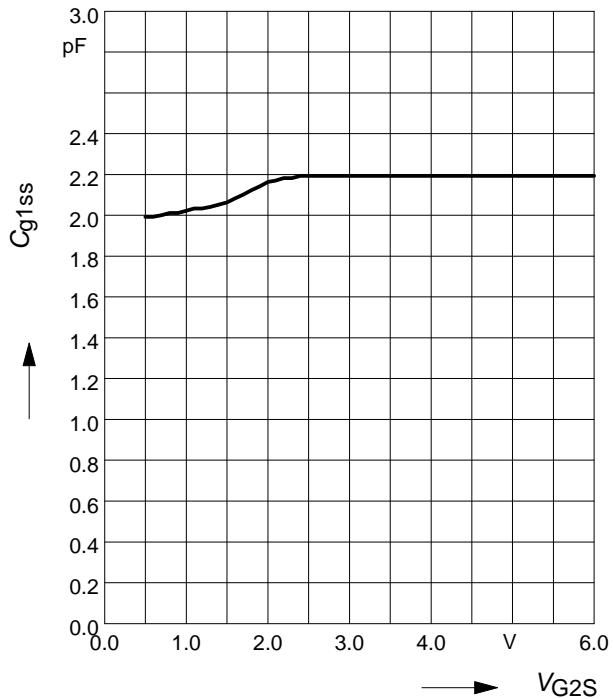


**Forward transfer admittance**

$$|Y_{21}| = f(V_{G2S})$$



**Gate 1 input capacitance**  $C_{g1ss} = f(V_{G2s})$   
 $f = 200\text{MHz}$



**Output capacitance**  $C_{dss} = f(V_{G2S})$   
 $f = 200\text{MHz}$

